WE CLAIM:

A method for producing an *in-situ* composite solder having an intermetallic phase comprising the steps of:

a) combining a solder with the components of the intermetallic phase to form a mixture;

- b) heating the mixture of step a) to form a non-solid;
- c) rapidly cooling the mixture of step b).
- 2. The method of Claim 1 where the solder matrix is a lead-free eutectic solder.
- 3. The method of Claim 1 where the solder matrix is a binary eutectic solder.
- 4. The method of Claim 1 where the solder matrix is a ternary eutectic solder.
- 5. The method of Claim 1 where the solder matrix is a near-eutectic solder.
 - 6. The method of Claim 1 where the eutectic solder-matrix is 96.5 Sn/3.5

7. The method of Claim 1 where the intermetallic phase comprises about

20 volume % of the composite solder.

8. The method of Claim 1 where the intermetallic phase comprises one of the elements of the eutectic solder and a transition metal.

- 9. The method of Claim 1 where the intermetallic phase comprises Cu_6Sn_5 .
 - 10. The method of Claim 1 where the intermetallic phase comprises Ni₃Sn₄.
 - 11. The method of Claim 1 where the intermetallic phase comprises FeSn₂.

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- 12. The method of Claim 1 where the mixture is heated to a temperature greater than the highest melting point of any of the individual mixture components.
- 13. The method of Claim 1 where the mixture is rapidly cooled by splat quenching.
- 14. The method of Claim 1 where the mixture is rapidly cooled by spray atomization.
- 15. The method of Claim—1 where the mixture is rapidly cooled by continuous casting into a solid form.
- 16. The method of Claim 1 where the non-solid mixture of step b) is cooled to form a solid and then heated to form a non-solid, prior to the rapid cooling of step c).
 - 17. A solder produced by the method of Claim 1.
- 18. The solder of Claim 17 comprising an intermetallic phase with particles less than about 10 microns.
- 19. The solder of Claim 17 comprising an intermetallic phase with particles less than about 2 microns